

DATA SHEET

74F804, 74F1804 Hex 2-input NAND drivers

Product specification

1990 Sep 14

IC15 Data Handbook

Hex 2-input NAND drivers

74F804/1804

FEATURES

- High capacitive drive capability
- Choice of configuration
 Corner V_{CC} and GND – 74F804
 Center V_{CC} and GND – 74F1804
- Typical propagation delay of 2.5ns

INPUT AND OUTPUT

LOADING AND FAN OUT TABLE

PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
Dna – Dnb	Data inputs	1.0/0.033	20 μ A/20 μ A
$\bar{Q}0 – \bar{Q}5$	Data outputs	2400/80	48mA/48mA

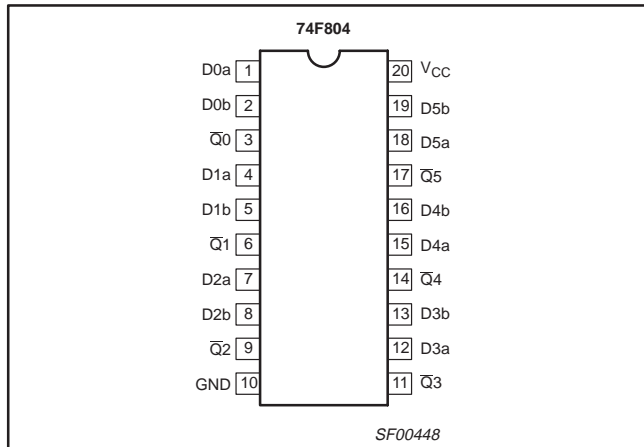
NOTE: One (1.0) FAST unit load is defined as: 20 μ A in the high state and 0.6mA in the low state.

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F804	2.5ns	9mA
74F1804	2.5ns	9mA

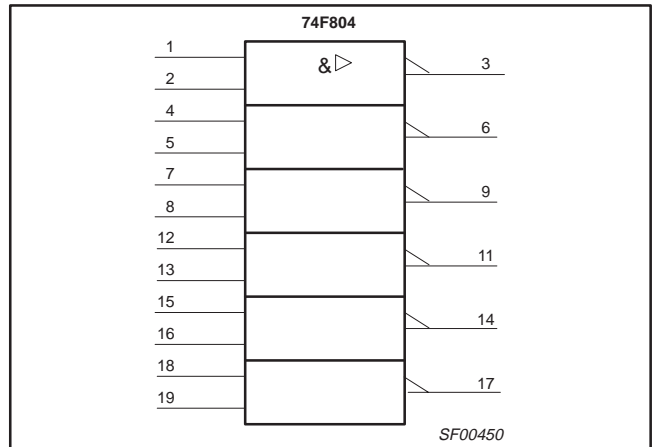
ORDERING INFORMATION

DESCRIPTION	ORDER CODE	PKG DWG #
	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$, $T_{amb} = 0^{\circ}C$ to $+70^{\circ}C$	
20-pin plastic DIP	N74F804N, N74F1804N	SOT146-1
20-pin plastic SOL	N74F804D, N74F1804D	SOT163-1

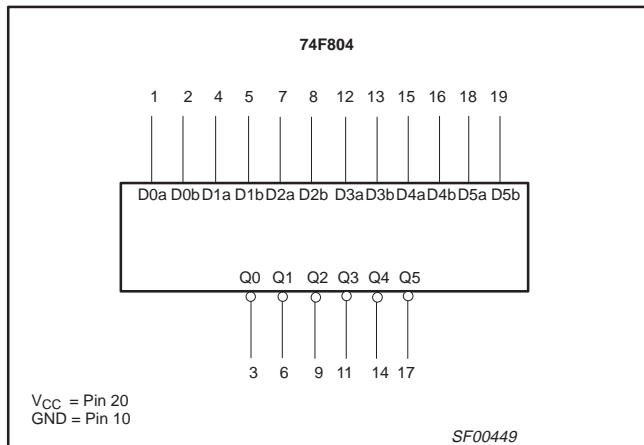
PIN CONFIGURATION



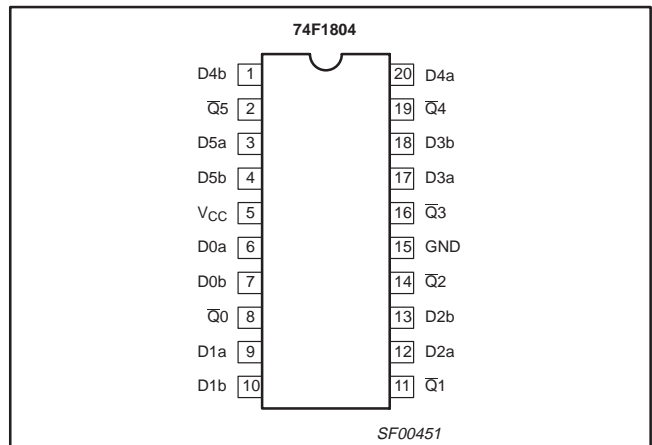
IEC/IEEE SYMBOL



LOGIC SYMBOL



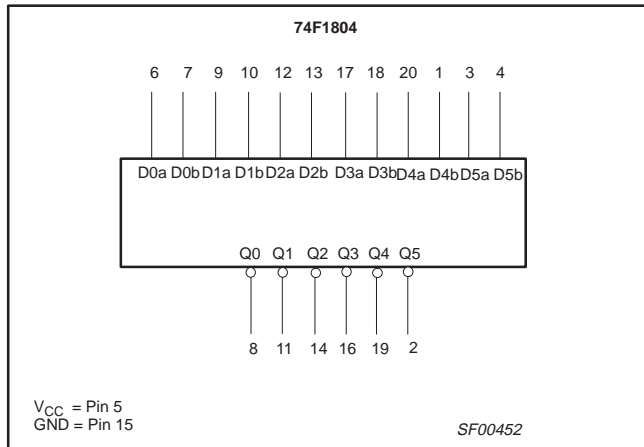
PIN CONFIGURATION



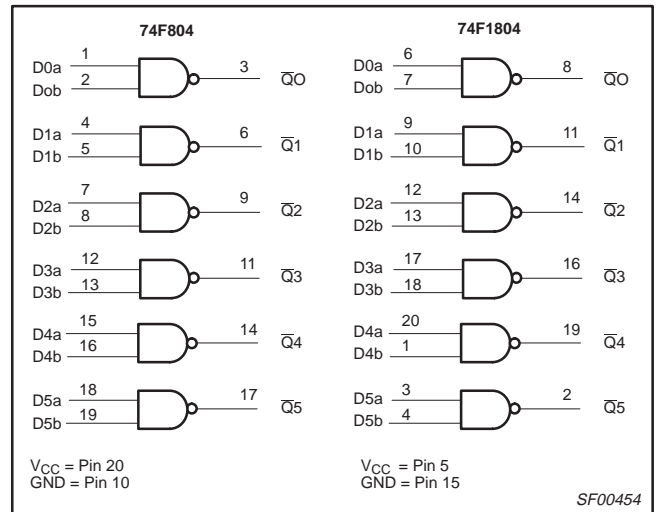
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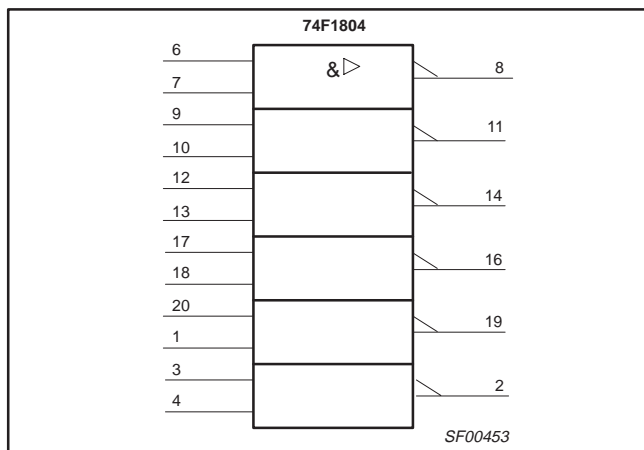
LOGIC SYMBOL



LOGIC DIAGRAM



IEC/IEEE SYMBOL



FUNCTION TABLE

INPUTS		OUTPUT
Da	Db	\bar{Q}
H	H	L
L	X	H
X	L	H

NOTES:

- H = High voltage level
- L = Low voltage level
- X = Don't care

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V_{CC}	Supply voltage	-0.5 to +7.0	V
V_{IN}	Input voltage	-0.5 to +7.0	V
I_{IN}	Input current	-30 to +5	mA
V_{OUT}	Voltage applied to output in high output state	-0.5 to V_{CC}	V
I_{OUT}	Current applied to output in low output state	96	mA
T_{amb}	Operating free-air temperature range	0 to +70	$^{\circ}C$
T_{stg}	Storage temperature range	-65 to +150	$^{\circ}C$

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RECOMMENDED OPERATING CONDITIONS

SYMBOL UNIT	PARAMETER	LIMITS			$T_A = -40$ to $+85^\circ\text{C}$
		MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5.0	5.5	V
V_{IH}	High-level input voltage	2.0			V
V_{IL}	Low-level input voltage			0.8	V
I_{IK}	Input clamp current			-18	mA
I_{OH}	High-level output current			-48	mA
I_{OL}	Low-level output current			48	mA
T_{amb}	Operating free air temperature range	0		+70	$^\circ\text{C}$

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS ¹	LIMITS			UNIT	
			MIN	TYP ²	MAX		
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}, V_{IL} = \text{MAX}$	$\pm 10\%V_{CC}$	2.0		V	
		$V_{IH} = \text{MIN}, I_{OH} = \text{MAX}$	$\pm 5\%V_{CC}$	2.0		V	
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}, V_{IL} = \text{MAX}$	$\pm 10\%V_{CC}$		0.38	0.55	V
		$V_{IH} = \text{MIN}, I_{OL} = \text{MAX}$	$\pm 5\%V_{CC}$		0.38	0.55	V
V_{IK}	Input clamp voltage	$V_{CC} = \text{MIN}, I_I = I_{IK}$		-0.73	-1.2	V	
I_I	Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 7.0\text{V}$			100	μA	
I_{IH}	High-level input current	$V_{CC} = \text{MAX}, V_I = 2.7\text{V}$			20	μA	
I_{IL}	Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.5\text{V}$			-20	μA	
I_O	Output current ³	$V_{CC} = \text{MAX}$	-60		-160	mA	
I_{CC}	Supply current (total)	I_{CCH} $V_{CC} = \text{MAX}$	$V_{IN} = \text{GND}$		2.0	3.0	mA
		I_{CCL} $V_{CC} = \text{MAX}$	$V_{IN} = 4.5\text{V}$		15	20	mA

NOTES:

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- All typical values are at $V_{CC} = 5\text{V}$, $T_{amb} = 25^\circ\text{C}$.
- The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

AC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITION	LIMITS					UNIT
			$T_{amb} = +25^\circ\text{C}$			$T_{amb} = 0^\circ\text{C to } +70^\circ\text{C}$		
			MIN	TYP	MAX	MIN	MAX	
t_{PLH} t_{PHL}	Propagation delay Dna, Dnb to Qn	Waveform 1	1.0 1.0	2.0 3.0	4.0 4.5	1.0 1.0	4.0 5.0	ns
$t_{sk(o)}$	Output skew ^{1,2}	Waveform 2			1.5		1.5	ns

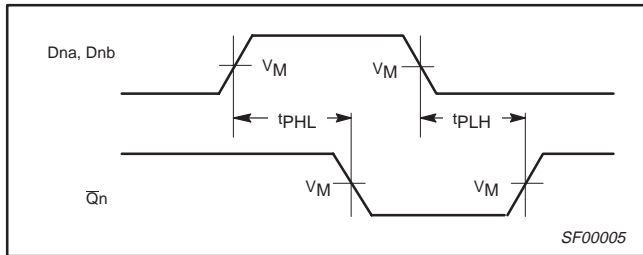
NOTES:

- $[t_{PN} \text{ actual} - t_{PM} \text{ actual}]$ for any output compared to any other output where N and M are either LH or HL.
- Skew times are valid only under same test conditions (temperature, V_{CC} , loading, etc.).

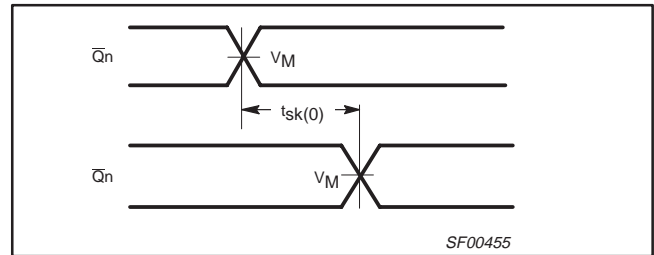
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AC WAVEFORMS



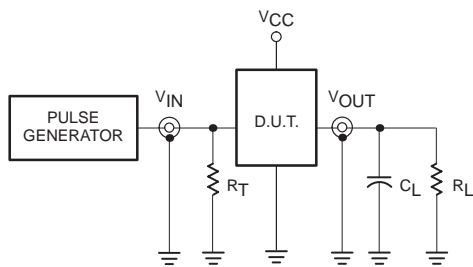
Waveform 1. Propagation delay for inverting outputs



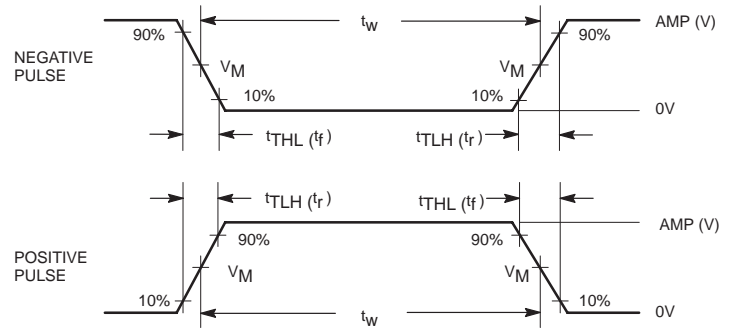
Waveform 2. Output skew

NOTE: For all waveforms, $V_M = 1.5V$.

TEST CIRCUIT AND WAVEFORMS



Test Circuit for Totem-Pole Outputs



Input Pulse Definition

DEFINITIONS:

- R_L = Load resistor; see AC ELECTRICAL CHARACTERISTICS for value.
- C_L = Load capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.
- R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

family	INPUT PULSE REQUIREMENTS					
	amplitude	V_M	rep. rate	t_w	t_{TLH}	t_{THL}
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns

SF00006

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DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

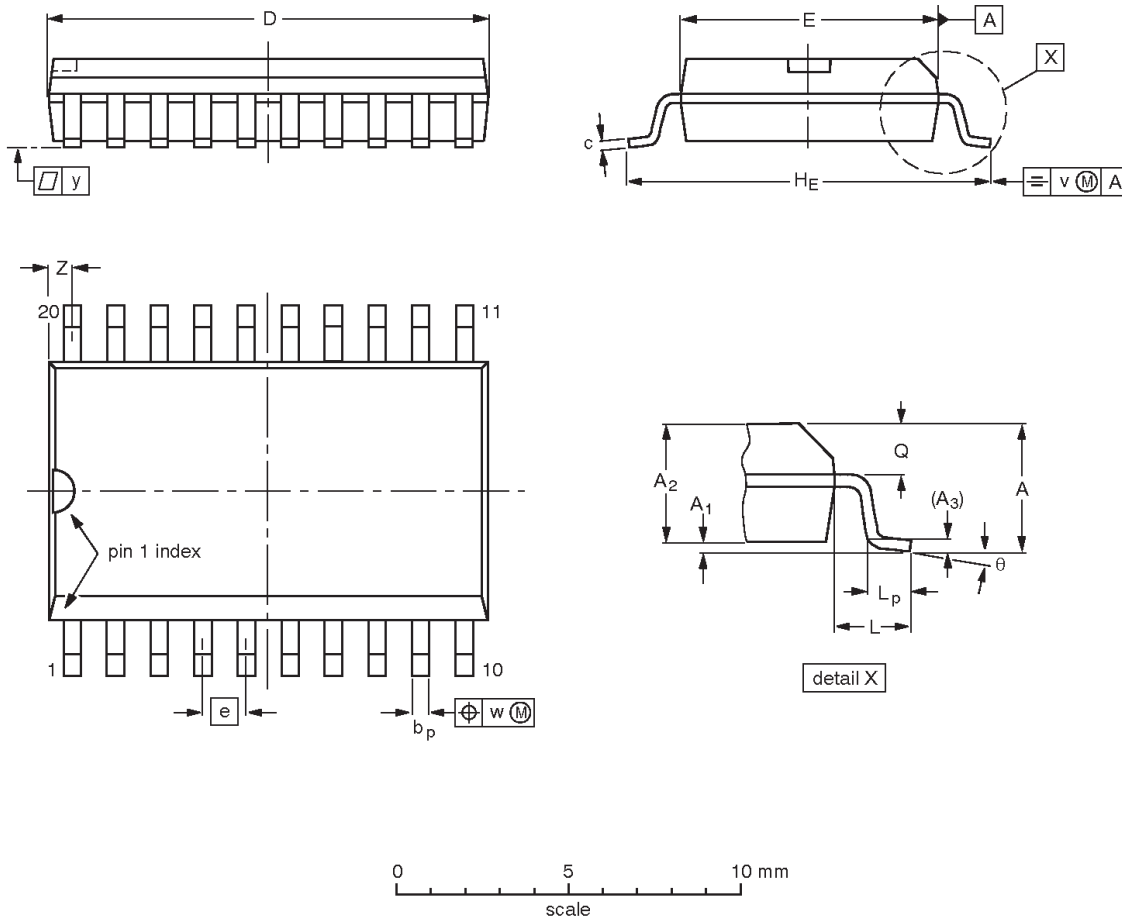
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT146-1			SC603			92-11-17 95-05-24

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SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				95-01-24 97-05-22

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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